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論文

超極細線でのワイヤ流れに及ぼす引張強度の影響

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The Effect of Tensile Strength on Wire Sweep of Ultra Fine Wires

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Abstract

In this study, we investigated the effect of wire strength on wire sweep after the semiconductor transfer molding assembly process. The wire sweep, loop height, and tensile strength of 25 μm, 20 μm, and 15 μm diameter wires were measured. As the tensile strength of 25 μm wires is higher, wire sweeps have a tendency to become smaller with 4.7 mm loops. However, such a trend is not shown in the case of 15 μm wires. It is found that the wire sweep of 15 μm wires depends on the loop height when the loop length is more than 4 mm, and it depends on the wire tensile strength when the loop length is less than 4 mm.

Key Words: *Bonding Wire, Wire Sweep, Wire Bonding, Molding, Tensile Strength*